HP Pro SFF 290 G9 Desktop PC

QuickSpecs

Overview

HP Pro SFF 290 G9 Desktop PC



- 1. Slim-height Bay supporting an optical disk drive (optional)
- 2. Power Button
- 3. Microphone/Headphone Combo Jack
- 4. (4) SuperSpeed USB 5Gbps signaling rate Ports¹

<u>Not shown</u>

Slots

(1) PCI Express4.0 x16
 (1) PCI Express3.0 x1
 (1) M.2 for WLAN
 (1) M.2 2230/2280 storage

1. SuperSpeed USB 5Gbps = USB3.2 Gen1

Bays (1) 3.5" (1) 9.5mm internal optical drive bay



HP Pro SFF 290 G9 Desktop PC

QuickSpecs

Overview

HP Pro SFF 290 G9 Desktop PC



- 1. Audio Line out
- 2. Audio Line in
- 3. VGA Port¹
- 4. Standard lock slot
- 5. HDMI Port¹

<u>Not Shown</u>

Parallel Port (Optional via PCIex1 slot) 4 Serial Port (Optional via PCIe slot) Intrusion Sensor (Optional)

1. Port will be covered up when configured with processor which is without internal graphics.

AT A GLANCE



6.

7.

8.

9.

Integrated accessories cable lock

(4) USB 2.0 ports

10. Power Cord Connector

11. Padlock Loop

Serial port (optional)

RJ-45 Network Connector

Overview

AT A GLANCE

- Windows 11 Pro 64, Win 11 Home 64 or FreeDOS.
- Intel[®] Intel[®] H670 chipset supporting up to Intel[®] 14th processors featuring Intel[®] UHD Graphics.
- Supports an optional discrete graphics card.
- Integrated 10/100/1000 Ethernet Controller or ac 2x2 +Bluetooth 5 M.2 2230 PCI-e+USB WW or 802.11ac (1x1) Wi-Fi[®] and Bluetooth[®] 4.2 Combo or Realtek 8852BE Wi-Fi6 +Bluetooth[®] 5.2 Screw WLAN.
- Up to 64GB DDR4-3200 Unbuffered Memory (UDIMM).
- Independent monitor support via VGA and HDMI interfaces.
- TPM 2.0 support (firmware)
- Supports both Hard Disk Drives and SATA TLC / PCIe[®] NVMe[™] M.2 SSD or PCIe[®] NVMe[™] TLC M.2 SSD.
- 8 USB Ports (including 4 SuperSpeed USB 5Gbps ports).
- 180W 85%/ 90% HE power supply and 240W 92% HE power supply¹.
- Security cable lock supported (sold separately).
- Intrusion sensor supported (optional).
- Optional HP Care Packs available; terms and conditions vary by country; certain restrictions and exclusions apply².

1. 180W 85%/90% available in select regions only.

2. HP Care Packs sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Standard Features and Configurable Modules

OPERATING SYSTEMS

Preinstalled Windows 11 Pro¹ Windows 11 Home - HP recommends Windows 11 Pro for Business¹ Windows 11 Home Single Language - HP recommends Windows 11 Pro for Business¹ FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

PROCESSORS*

Intel 13th Processors

Intel[®] Core™ i3^{1,2,3}

CPU Intel Core i3-13100 4C 3.4GHz 3200MHz 60W (3.4GHz, turbo up to 4.5GHz, 12MB cache, 4 cores)

Intel[®] Core™ i5^{1,2,3}

CPU Intel Core i5-13400 10C 2.5GHz 3200MHz 65W (2.5GHz, turbo up to 4.6GHz, 20MB cache, 10 cores) CPU Intel Core i5-13400F 10C 2.5GHz 3200MHz 65W (2.5GHz, turbo up to 4.6GHz, 20MB cache, 10 cores) CPU Intel Core i5-13500 14C 2.5GHz 3200MHz 65W (2.5GHz, turbo up to 4.8GHz, 24MB cache, 14 cores) CPU Intel Core i5-13600 14C 2.7GHz 3200MHz 65W (2.7GHz, turbo up to 5.0GHz, 24MB cache, 14 cores)

Intel® Core™ i7^{1,2,3}

CPU Intel Core i7-13700 16C 2.1GHz 3200MHz 65W (2.1GHz, Up to 5.2GHz with Intel® Turbo Boost⁴, 30MB cache, 16 cores)

Intel 14th Processors

Intel® Core™ i3^{1,2,3}

Intel[®] Core[™] i3-14100 with Intel UHD Graphics 730 (3.5 GHz P-core base frequency, up to 4.7 GHz P-core Max Turbo frequency, 12 MB L3 cache, 4 P-cores, 8 threads)

Intel[®] Core™ i5^{1,2,3}

Intel[®] Core[™] i5-14600 with Intel UHD Graphics 770 (2.0 GHz E-core base frequency, 2.7 GHz P-core base frequency, up to 3.9 GHz E-core Max Turbo frequency, up to 5.2 GHz P-core Max Turbo frequency, 24 MB L3 cache, 6 P-cores and 8 E-cores, 20 threads), supports Intel[®] vPro[®] Technology

Intel[®] Core[™] i5-14500 with Intel UHD Graphics 770 (1.9 GHz E-core base frequency, 2.6 GHz P-core base frequency, up to 3.7 GHz E-core Max Turbo frequency, up to 5.0 GHz P-core Max Turbo frequency, 24 MB L3 cache, 6 P-cores and 8 E-cores, 20 threads), supports Intel[®] vPro[®] Technology

Intel[®] Core[™] i5-14400 with Intel UHD Graphics 730 (1.8 GHz E-core base frequency, 2.5 GHz P-core base frequency, up to 3.5 GHz E-core Max Turbo frequency, up to 4.7 GHz P-core Max Turbo frequency, 20 MB L3 cache, 6 P-cores and 4 E-cores, 16 threads)

Intel[®] Core™ i7^{1,2,3}

Intel[®] Core[™] i7-14700 with Intel UHD Graphics 770 (1.5 GHz E-core base frequency, 2.1 GHz P-core base frequency, up to 4.2 GHz E-core Max Turbo frequency, up to 5.3 GHz P-core Max Turbo frequency, 33 MB L3 cache, 8 P-cores and 12 E-cores, 28 threads), supports Intel[®] vPro[®] Technology



Standard Features and Configurable Modules

1. Your product does not support Windows 8 or Windows 7, In accordance with Microsoft's support policy, HP does not support the Windows[®] 8 or Windows 7 operating system on products configured with Intel 8th generation and forward processors or provide any Windows[®] 8 or Windows 7 drivers on http://www.support.hp.com

2. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

 In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.
 Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system. See http://www.intel.com/technology/turboboost for more information.
 *NOTE: Not all processors are available; it varies by version.



Standard Features and Configurable Modules

CHIPSET

Intel[®] H670 Chipset

GRAPHICS

Integrated^{1,2}

Intel[®] UHD Graphics 770 Graphics 730 Graphics 710

Discrete Graphics

AMD Radeon[™] RX 6300XT Graphics (2 GB GDDR6)

1. HD content required to view HD images.

2. Integrated Intel software is available on select models only and requires separately purchased projector, tv or computer monitor with an integrated or external receiver. External receivers connect to the projector, tv or computer monitor via a standard VGA, HDMI cable, also sold separately.

MEMORY

Both slots are customer accessible / upgradeable, Supports Dual Channel Memory

Form Factor	Туре	Maximum	# of Slots
Small Form Factor	DDR4 3200	64 GB capacity	2 DIMM ¹
4GB DDR4-3200 UDIMM NECC 8GB DDR4-3200 UDIMM NECC 8GB DDR4-3200 UDIMM NECC 16GB DDR4-3200 UDIMM NEC 32GB DDR4-3200 UDIMM NEC 32GB DDR4-3200 UDIMM NEC 64GB DDR4-3200 UDIMM NEC	(1x8GB) (2x4GB) (C (1x16GB) (C (2x8GB) (C (1x32GB) (C (2x16GB)		

1. Memory modules support data transfer rates up to 3200 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.



Standard Features and Configurable Modules

STORAGE AND DRIVES

NOTE: Starting from November 1st, 2023, all shipments will require Windows to be installed when selecting a SSD. HDD can only be configured as additional data drives and not as the boot drive.

SATA3 - 3.5" 6Gb/s HDDs*

2TB 7200 RPM SATA Hard Disk Drive

1TB 7200 RPM SATA Hard Disk Drive

1. Available on select skus only.

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

M.2 Solid State Drives

256GB* M.2 NVMe 512GB* M.2 NVMe 1TB* M.2 NVMe 128GB* M.2 2280 PCIe NVMe Three Layer Cell SSD ¹ 256GB* M.2 2280 PCIe NVMe Three Layer Cell SSD 512GB* M.2 2280 PCIe NVMe Three Layer Cell SSD 1TB* M.2 2280 PCIe NVMe Three Layer Cell SSD

1. Available on select skus only.

NOTE*: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

OPTICAL DISC DRIVES

DVD-ROM 9.5mm² DVD-Writer 9.5mm²

2. Optical drives are optional or add on features. HD-DVD disks cannot be played on this drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials.

NETWORKING/COMMUNICATIONS

Networking

Integrated 10/100/1000M GbE LAN

Wi-Fi[®] and Bluetooth[®]

Realtek RTL8852BE 802.11 a/b/g/n/ac/ax (2x2) Wi-Fi6 and Bluetooth 5.3 Wireless Card¹ Realtek RTL8822CE-CG 802.11 a/b/g/n/ac (2x2) Wi-Fi5 and Bluetooth 5.0 Wireless Card² Realtek RTL8821CE-CG 802.11 a/b/g/n/ac (1x1) Wi-Fi5 and Bluetooth 4.2 Wireless Card²

Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.
 Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.



Standard Features and Configurable Modules

AUDIO/MULTIMEDIA

Realtek ALC3867-CG Integrated Hi-Definition Audio Combo Jack, Headphone/ Microphone

Line-in/ Line-out (3.5mm)



Standard Features and Configurable Modules

KEYBOARDS/POINTING DEVICES/BUTTONS AND FUNCTIONS KEYS

Keyboard

HP USB 320K Keyboard HP 125 Wired Keyboard HP 125 Antimicrobial Wired Keyboard

Mouse

HP Wired Desktop 320M mouse HP 125 Wired Mouse HP 128 Laser Wired Mouse HP 125 Antimicrobial Wired Mouse (China only)

PORTS

Front

Slim-height Bay - supporting an optical disk drive (optional) (4) SuperSpeed USB 5Gbps signaling rate Microphone/Headphone Combo Jack Power Button

Not Shown

(1) PCI Express4.0 x16
(1) PCI Express3.0 x1
(1) M.2 for WLAN
(1) M.2 2230/2280 storage

Rear

Audio Line out Audio Line in HDMI Port Standard lock slot VGA Port (4) USB 2.0 port RJ-45 Network Connector Power Cord Connector Padlock loop Integrated Accessories Cable Lock Serial port (optional)



Standard Features and Configurable Modules

Not Shown

(1) Parallel Port (Optional via PCIex1 slot)
 (1) 4x Serial port (Optional via PCIex1 slot)¹
 (1) PS/2 Port (Optional)
 (1) Intrusion Sensor (Optional)

1. Available for selected regions

BAYS

(1) 3.5" internal storage

(1) 9.5mm internal optical drive bay

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Security and Protection

McAfee* LiveSafe^{™1}

Productivity

Microsoft 365 (sold separately and requires Internet access for activation) Dropbox²

ODD Playback

sMedio True DVD for HP

App Stores and Content Purchasing

Amazon⁴

HP Utilities and Support

HP Documentation HP JumpStarts HP Audio Switch⁵ HP Support Assistant⁶ myHP

BTB

HP Setup Integrated OOBE

Hardware Enabling Drivers or software utility

HP System Event Utility

***NOTE**: Available for LA region only.

1. Free 1-year subscription of McAfee LiveSafe service included. Internet access required and not included. Subscription required after expiration 2. New Dropbox users are eligible to get 25 GB of Dropbox space free for 12 months from date of registration. For complete details and terms of use, including cancellation policies, visit the Dropbox website at https://www.dropbox.com/help/space/hp-promotion. Internet service required and not included.

3. Simply sign up and start using Xerox[®] DocuShare[®] Go. No credit card. No obligation. Data will become unavailable unless a subscription is



Standard Features and Configurable Modules

entered before the end of the 30 day free trial period. See visit http://www.xerox.com/docusharego for details.

4. Internet access required and not included.

5. Easily switch between speaker and microphone sources with intuitive controls and a consistent app experience

6. For more information visit hp.com/go/hpsupportassistant [Link will vary outside of the U.S.] HP Support Assistant is available for Android and Windows based PCs.

POWER

Power Supply 180W EPA85 Full range 115V/230V EPA90 Full range 115V/230V

240W EPA92 Full range

WEIGHT AND DIMENSIONS

(configured with 1 HDD and 1 ODD)

Chassis (W x D x H) 3.74 x 11.93 x 10.63 in (95 x 303 x 270 mm) (w/bezel)

System Weight 8.82 lbs / 4 kg*

*NOTE: Weight varies by configuration and component

UNIT ENVIRONMENTAL AND OPERATING CONDITIONS

General Unit Operating Guidelines

denerationit operating de	nuclines	
Environmental and Industry	 Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range. Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow. Never restrict airflow into the computer by blocking any vents or air intakes. Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air. Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow. If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply. 	
Temperature Range	Operating:	5° to 35° C ¹
	Non-operating:	-30° to 60°1
Relative Humidity	Operating:	5% to 90% (non-condensing at ambient)
	Non-operating:	5% to 90% (non-condensing at ambient)
Maximum Altitude	Operating:	5,000 m
(unpressurized)	Non-operating:	50,000 ft (15240 m)

1. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.



Standard Features and Configurable Modules

Eco-Label Certifications & declarations	 This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR[®] US Federal Energy Management Program (FEMP) EPEAT Silver registered in the United States. See http://www.epeat.net for registration status in your country. China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Commission Regulation (EC) No 617/2013 (ErP Lot 3) 		
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop".		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	12.46W	12.51W	12.40W
Normal Operation (Long idle)	10.16W	10.22W	10.02W
Sleep	1.76W	1.75W	1.76W
Off	0.38W	0.41W	0.41W
Hoat Discipation*	configured PC featuring a hard disk driv operating system. Search keyword ger at http://www.hp.com/go/options.	erator on HP's 3rd party option s	
Heat Dissipation* Normal Operation (Short idle)	115VAC, 60Hz 42.49 BTU/hr	230VAC, 50Hz 42.66 BTU/hr	42.28 BTU/hr
Normal Operation (Long idle)	34.65 BTU/hr	34.85 BTU/hr	34.17 BTU/hr
Sleep	6.00 BTU/hr	5.97 BTU/hr	6.00 BTU/hr
Off	1.30 BTU/hr	1.40 BTU/hr	1.40 BTU/hr
	NOTE: Heat dissipation is calculated ba		
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound PowerSound Pressure(LwAd, bels)(LpAm, decibels)		
Typically Configured – Idle	3.2 19.7		19.7
Fixed Disk – Random writes	3.3 20.7		20.7
Optical Drive – Sequential reads	4.5 38.2		
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "3" years after the end of production.		
Batteries	This battery(s) in this product com	oly with EU Directive 2006/66/	'EC
	Batteries used in the product do no Mercury greater the1ppm by weigh Cadmium greater than 20ppm by w	it	



Standard Features and Configurable Modules

	Battery size: CR2032 (coi	in cell)	
	Battery type: Lithium		
Additional Information	 This product is in complexity 2011/65/EC. This HP product is designed (WEEE) Directive – 2002/ This product is in complexity and Toxic Enforcer This product is in complexity and the toxic Enforcer This product is in complexity and the toxic Enforcer This product is in complexity and the toxic Enforcer This product is in complexity and the toxic Enforcer This product contains 2 	liance with California Proposition 65 (State of Califo ment Act of 1986). liance with the IEEE 1680.1 (EPEAT) standard at the over 25 grams used in the product are marked per 8.2% post-consumer recycled plastic (by wt.)	onic Equipment ornia; Safe Drinking e <silver> level, see ISO11469 and</silver>
De else else e Med este le		ecycle-able when properly disposed of at end of life	
Packaging Materials	External:	PAPER/Corrugated	540 g
	internat:		
Material Usage Packaging Usage	Internal: PAPER/Molded Pulp 350 g Internal: PAPER/Molded Pulp 350 g This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): 30 g • Asbestos • Certain Azo Colorants • Certain Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead carbonates and sulfates • Lead carbonates and sulfates • Lead carbonates must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBS) • Polybrominated Biphenyl (PCB) • Polybrominated Biphenyl (PCB) • Polybrominated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polychlorinated Terphenyls (PCT) • Polychlorinated Terphenyls (PCT) • Polychlorinated Terphenyls (PCT) • Polychlorinated Terphenyls (PCT) • Polychlorinated Terphenyls (
	materials. • Eliminate the use of ozo • Design packaging mate • Maximize the use of pos • Use readily recyclable p • Reduce size and weight	avy metals such as lead, chromium, mercury and ca one-depleting substances (ODS) in packaging mate rials for ease of disassembly. st-consumer recycled content materials in packagin packaging materials such as paper and corrugated r of packages to improve transportation fuel efficien rials are marked according to ISO 11469 and DIN 61	rials. ng materials. naterials. ncy.



Standard Features and Configurable Modules

End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_1 4K_Certificate.pdf and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

SERVICE AND SUPPORT

On-site Warranty¹: Available three-year (3-3-3) or one-year (1-1-1) limited warranty (varies by country) delivers on-site, next business day² service for parts and labor and complimentary limited technical support³. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Service⁴. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.

Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
 On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
 Technical support applies only to HP-configured and third-party HP qualified hardware and software.

4. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

GRAPHICS

GRAPHICS

Graphics Controller	Integrated
DisplayPort™	Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 4 displays connected to any output controlled by Intel® Graphics
HDMI	Supports HDMI 2.0a features Supports HDCP 2.2 Supports audio over HDMI
VGA	VGA output
Memory	The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Color Depth	up to 10 bits/color
Graphics/Video API Support	HEVC 10b Enc/Dec HW VP9 10b Dec HW
	HDR Rec. 2020 DX12
Supported Display Resolutions	Max. Resolution (VGA) 2048 x 1536 @60Hz
and Refresh Rates	Max. Resolution (HDMI) 7680 x 4320 @60Hz
Note: The actual amount of maximum configuration.	max. Resolution (HDMI) 7680 x 4320 @60HZ n graphics memory can be less than the amounts listed above depending upon your computer's

Note: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP Only supported on displays connected to the external DisplayPort[™] connector.

AMD® Radeon™ RX 6300 2GB Graphics Card

Engine Clock	1512 MHz (Game) 2040MHz (Boost)
Memory Clock	2000 MHz
Memory Size(width)	2GB
Memory Type	512M x 32 GDDR6
Max. Resolution (HDMI)	7680x4320x36bpp @60Hz
Max. Resolution (DP)	7680x4320x24bpp @120Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors (bracket)	HDMIx1+DPx1
Cooling (active/passive)	Active fan-sink
Total power consumption (W)	32W
PCB form-factor with bracket FH	LP PCB with LP/FH bracket



Technical Specifications – Storage

STORAGE

NOTE: Starting from November 1st, 2023, all shipments will require Windows to be installed when selecting a SSD. HDD can only be configured as additional data drives and not as the boot drive.

HP 2TB* 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive*

Capacity	2TB
Rotational Speed	7,200 rpm
Interface	SATA 6Gb/s NCQ
Buffer Size	64 MB
Logical Blocks	3,907,029,168
Seek Time	Read: <8.5 ms
	Write: <9.5 ms
Height	1.028 in/26.11 mm
Width	4.0 in/101.6 mm
Operating Temperature	32° to 140° F (0° to 60° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

1TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity	1TB
Rotational Speed	7,200 rpm
Interface	Serial ATA 3.0 (6.0 Gb/s)
Buffer Size	32 MB
Logical Blocks	1,953,525,168
Seek Time	Read: <8.5 ms
	Write: <9.5 ms
	Full-Stroke: 21 ms
Height	1 in/2.54 cm
Width	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

128GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	128GB
Height	2.38mm
Length	80mm
Width	22mm



Technical Specifications – Storage

Interface	PCIE Gen3x4
Maximum Sequential Read	Up to 2800MB/s
Maximum Sequential Write	Up to 600MB/s
Logical Blocks	250,069,680
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	256GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3x4
Maximum Sequential Read	Up to 2700MB/s
Maximum Sequential Write	Up to 1000MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.



Technical Specifications – Storage

512GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	512GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3x4
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

1TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight Capacity Height	< 10g <u>1T</u> B 2.3mm
Length	80mm
Width	22mm
Interface	PCIE <u>NVMe</u>
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	<u>2,000,409,264</u>
Operating Temperature Features	0° to 70°C (32° to 158°F) [ambient temp] <u>Pyrite</u>

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

256GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	256GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 780MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2



Technical Specifications – Storage

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

512GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	512GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 860MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

1TB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	<u>1T</u> B
Height	2.3mm
Length	80mm
Width	22mm
Interface	PCIE N <mark>VMe</mark>
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write Logical Blocks	Up to 860MB/s <u>2</u> ,000, <u>409</u> ,2 <u>64</u>
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	<u>Pyrite</u>

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

1TB 7200RPM 2.5in SATA HDD

Capacity	1TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	32 MB
Logical Blocks	1,953,525,168
Seek Time	12 ms (Average)
Height	0.374 in/9.5 mm (nominal)
Width (nominal)	2.75 in/70 mm (nominal)



Technical Specifications – Storage

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

Technical Specifications – Optical Disc Drives

OPTICAL DISC DRIVES

HP 9.5mm Desktop G2 Slim DVD Writer Drive

Height Orientation Interface type Disc recording capacity Dimensions (W x H x D) Weight (max) Read Speeds	9.5 mm height Either horizontal or vertical SATA/ATAPI Up to 8.5 GB DL or 4.7 GB standard 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel 0.31 lb (140 g) DVD-R DL - Up to 6X DVD+R - Up to 8X DVD+R V - Up to 8X DVD+R DL - Up to 6X DVD-R V - Up to 6X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X DVD-RW, DVD+R W - Up to 8X DVD-RW, DVD+R DL - Up to 8X DVD-R DL, DVD+R DL - Up to 8X DVD-ROM DL, DVD-ROM - Up to 8X
	CD-ROM, CD-R – Up to 24X CD-RW – Up to 24X
Access time (typical reads, including settling)	Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Desktop G2 Slim DVD-ROM Drive

Height	9.5 mm height
Orientation	Either horizontal or vertical
Interface type	SATA/ATAPI
Disc recording capacity	Up to 8.5 GB DL or 4.7 GB standard
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel
Weight (max)	0.31 lb (140 g)
Read Speeds	DVD-R DL - Up to 6X DVD+R - Up to 8X DVD+RW - Up to 8X DVD+R DL - Up to 6X DVD-R - Up to 8X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X



Technical Specifications – Optical Disc Drives

	DVD-RW, DVD+RW - Up to 8X DVD-R DL, DVD+R DL - Up to 8X DVD+R, DVD-R - Up to 8X DVD-ROM DL, DVD-ROM - Up to 8X CD-ROM, CD-R - Up to 24X CD-RW - Up to 24X
Access time (typical reads, including settling)	Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)



Technical Specifications – Audio

HIGH DEFINITION AUDIO

Туре	Integrated
HD Audio Codec	Realtek ALC3867-CG
Audio I/O Ports	Front side Combo jack for supporting CTIA, Rear side Line-in/ Line-out/ Mic-in jacks
Wavetable Syntheses	Yes
Analog Audio	Yes
Internal Speaker	NA
DAC Sampling Rates	16 to 24-bit; 44.1K/ 48 K/96K / 192K Hz
ADC Sampling Rates	16 bit, 44.1K/ 48K/ 96K/ 192K Hz

Technical Specifications - Power

P/S 180W SFF ENTS20L EAP	85
Operating Voltage Range	180 – 264 VAC
Rated Voltage Range	200-240V AC
Rated Line Frequency	50/60 HZ
Operating Line Frequency	47 – 63 Hz
Rated Input Current	180W: <1.3A
Rated Input Current with Energy Efficient* Power Supply	82/85/82% efficient at 20/50/100% load (230V)
DC Output	+12.1V
Current Leakage (NFPA 99: 2102)	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
Power Supply Fan	50 x 20 mm (linear type)

P/S 180W SFF ENTS20L EAP90

90 – 264 VAC
100-240V AC
50/60 HZ
47 – 63 Hz
180W: <2.3A
87/90/87% efficient at 20/50/100% load (115Vac) 88/92/88% efficient at 20/50/100% load (230V)
+12.1V
Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
50 x 20 mm (linear type)

P/S 240W SFF ENTS20L EAP92

Operating Voltage Range	90 – 264 VAC
Rated Voltage Range	100-240V AC
Rated Line Frequency	50/60 HZ
Operating Line Frequency	47 – 63 Hz
Rated Input Current	240W Platinum \leq 2.9A



Technical Specifications - Power

Rated Input Current with Energy Efficient* Power Supply	90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)
DC Output	+12V
Current Leakage (NFPA 99: 2102)	Less than 500 microamps of leakage current at 264 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 264 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
Power Supply Fan	50mm variable speed

Technical Specifications – Weights and Dimensions

WEIGHTS AND DIMENSIONS

Chassis (W × D × H)	3.74 x 11.93 x 10.63 in (95 x 303 x 270 mm) (w/ bezel)
System Volume	463.16cu in 7.6L
System Weight*	8.82 lbs / 4 kg
Packaged (H x W x D)	13.46 x 7.72 x 19.65 in 342 x 196 x 499 mm
Shipping Weight*	13.2 lb / 6 kg
Shipping Weight (Molded Pulp)*	13.86 lb / 6.3 kg
Palletization Profile	12-units per layer 6 layer max 72 per pallet Footprint (HxWxD) 85.91 x 39.37 x 47.24 in (2182 x 1000 x 1200 mm)

***NOTE**: Weight varies by configuration and component



Technical Specifications – Networking

NETWORKING

10/100/1000 Integrated NIC	
Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
Performance Features	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status

Realtek RTL8821CE-CG 802.11 a/b/g/n/ac (1x1) Wi-Fi5 and Bluetooth® 4.2 Wireless Card

-		
Wireless LAN Standards1		int and internet service required and sold separately. Availability of public wireless . Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.
Interoperability	Wi-Fi [®] certified mo	dules
Frequency Bands	802.11b/g/n	•2.402 – 2.482 GHz Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
	802.11a/n	•4.9 – 4.95 GHz (Japan) •5.15 – 5.25 GHz •5.25 – 5.35 GHz •5.47 – 5.725 GHz •5.825 – 5.850
Data Rates	•802.11g:•802.11a:	1, 2, 5.5, 11 Mbps 6, 9, 12, 18, 24, 36, 48, 54 Mbps 6, 9, 12, 18, 24, 36, 48, 54 Mbps MCS 0 ~ MCS 15, (20MHz, and 40MHz)



	• •802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ²	• •IEEE and 64 / 128 bit WEP encryption for a/b/g mode only
	• AES-CCMP: 128 bit in hardware
	• •802.1x authentication
	 •WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	• WPA2 certification
	• •IEEE 802.11i
	 • Cisco Certified Extensions, all versions through CCX4 and CCX Lite
	• •WAPI
	2 Check latest software/driver release for updates on supported security features.
Network Architecture	Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ³	• • 802.11b: +14dBm minimum
	• • 802.11g: +12dBm minimum
	• • 802.11a: +12dBm minimum
	 • 802.11n HT20(2.4GHz): +12dBm minimum
	 • 802.11n HT40(2.4GHz): +12dBm minimum
	 • 802.11n HT20(5GHz): +10dBm minimum
	 • 802.11n HT40(5GHz): +10dBm minimum
	 • 802.11ac VHT80(5GHz): +10dBm minimum
	3. Maximum output power may vary by country according to local regulations.
Power Consumption	•Transmit mode2.0 W
	•Receive mode1.6 W
	 Idle mode (PSP)180 mW(WLAN Associated) Idle mode50 mW(WLAN unassociated)
	•Connected Standby 10mW
	•Radio disabled8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum
-	802.11b, 11Mbps: -84dBm maximum
	802.11a/g, 6Mbps: -86dBm maximum
	802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum
	802.11n, MCS07670Bin maximum 802.11n, MCS15: -64dBm maximum
	802.11ac, MCS0: -84dBm maximum



Technical Specifications – Networking

	802.11ac, MCS9: -59dBm maxi	mum	
		4 Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).	
Antenna type	High efficiency antenna. One embedded dual band 2.4/5 communications and Bluetooth	5 GHz antenna is provided to the card to support WLAN n communications	
Form Factor	PCI-Express M.2 MiniCard	PCI-Express M.2 MiniCard	
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm		
Weight	Туре 2230: 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating: Non-operating:	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)	
Humidity	Operating: Non-operating:	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating: Non-operating:	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF; LED White – Radio ON		

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Receiver Sensitivity Legacy	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Range	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Electrical Interface	USB 2.0 compliant



Technical Specifications – Networking

Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support
Certifications Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Realtek RTL8822CE-CG 802.11 a/b/g/n/ac (2x2) Wi-Fi5 and Bluetooth® 5.0 Wireless Card

Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
	1. Wireless access point and internet service required and sold separately. Availability of public
	wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.
Interoperability	Wi-Fi [®] certified
Frequency Band	802.11b/g/n
	• 2.402 – 2.482 GHz
	802.11a/n/ac
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz



Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	• 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ²	• IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode only
	AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	 WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification
	• IEEE 802.11i
	• WAPI
	2 Check latest software/driver release for updates on supported security features.
Network Architecture Models	Ad-hoc (Peer to Peer)
Network Architecture Mouels	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ³	• 802.11b: +18.5dBm minimum
	• 802.11g: +17.5dBm minimum
	• 802.11a: +18.5dBm minimum
	• 802.11n HT20(2.4GHz): +15.5dBm minimum
	• 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum
	• 802.11n HT40(5GHz): +14.5dBm minimum
	• 802.11ac VHT80(5GHz): +11.5dBm minimum
	• 802.11ac VHT160(5GHz): +11.5dBm minimum
	3. Maximum output power may vary by country according to local regulations.
Power Consumption	Transmit mode:2.0 W
rower consumption	Receive mode:1.6 W
	• Idle mode (PSP) 180 mW (WLAN Associated)
	• Idle mode:50 mW (WLAN unassociated)
	Connected Standby/Modern Standby: 10mW
	• Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management
-	802.11 compliant power saving mode
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum
	802.11b, 11Mbps: -84dBm maximum
	802.11a/g, 6Mbps: -86dBm maximum
	802.11a/g, 54Mbps: -72dBm maximum
	802.11n, MCS07: -67dBm maximum
	802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum
	802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum
	4 Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a
	packet error rate of 10% for 802.11a/g (OFDM modulation).



Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8g 2. Type 126: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (–10° to 70° C) Non-operating: –40° to 176° F (–40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON
	uetooth 4.0/4.1/4.2/5.0 Wireless Technology
Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
	Missocoft Mindows ACDL and USD Dus Support
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC60950-1/IEC62368-1 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising



Technical Specifications – Networking

LE L2CAP Connection Oriented Channels
Train Nudging & Interlaced Scan
BT4.2 ESR08 Compliance
LE Secure Connection- Basic/Full
LE Privacy 1.2 –Link Layer Privacy
LE Privacy 1.2 – Extended Scanner Filter Policies
LE Data Packet Length Extension
FAX Profile (FAX)
Basic Imaging Profile (BIP)2
Headset Profile (HSP)
Hands Free Profile (HFP)
Advanced Audio Distribution Profile (A2DP)

Realtek RTL8852BE 802.11 a/b/g/n/ac/ax (2x2) Wi-Fi6 and Bluetooth® 5.3 Wireless Card¹

Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11h IEEE 802.11k IEEE 802.11r IEEE 802.11v 1. Wireless access point and Internet service required and sold separately. Availability of public		
Interoperability	wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.		
Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n/ac • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz		
Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz) 		
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		



Security ²	 IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 	
	• 802.1x authentication	
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.	
	WPA2 certification	
	• IEEE 802.11i	
	• WAPI	
	2 Check latest software/driver release for updates on supported security features.	
Network Architecture Models	Ad-hoc (Peer to Peer)	
	Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	
Output Power ³	• 802.11b: +18.5dBm minimum	
	• 802.11g: +17.5dBm minimum	
	• 802.11a: +18.5dBm minimum	
	• 802.11n HT20(2.4GHz): +15.5dBm minimum	
	• 802.11n HT40(2.4GHz): +14.5dBm minimum	
	• 802.11n HT20(5GHz): +15.5dBm minimum	
	• 802.11n HT40(5GHz): +14.5dBm minimum	
	• 802.11ac VHT80(5GHz): +11.5dBm minimum	
	• 802.11ac VHT160(5GHz): +11.5dBm minimum	
	3. Maximum output power may vary by country according to local regulations.	
Power Consumption	• Transmit mode:2.0 W	
	Receive mode:1.6 W	
	• Idle mode (PSP) 180 mW (WLAN Associated)	
	• Idle mode:50 mW (WLAN unassociated)	
	Connected Standby/Modern Standby: 10mW	
	• Radio disabled: 8 mW	
Power Management	ACPI and PCI Express compliant power management	
	802.11 compliant power saving mode	
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum	
2	802.11b, 11Mbps: -84dBm maximum	
	802.11a/g, 6Mbps: -86dBm maximum	
	802.11a/g, 54Mbps: -72dBm maximum	
	802.11n, MCS07: -67dBm maximum	
	802.11n, MCS15: -64dBm maximum	
	802.11ac, MCS0: -84dBm maximum	
	802.11ac, MCS9: -59dBm maximum	
	4 Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a	
	packet error rate of 10% for 802.11a/g (OFDM modulation).	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure	
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN	
	MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm	
	2. Type 1216: 1.67 x 12.0 x 16.0 mm	
	2. Type 1210. 1.07 x 12.0 x 10.0 mm	



	T		
Weight	1. Type 2230: 2.8g 2. Type 126: 1.3g		
Operating Voltage	2. Type 126: 1.3g 3.3v +/- 9%		
Temperature	Operating: 14° to 158° F (–10° to 70° C) Non-operating: –40° to 176° F (–40° to 80° C)		
Humidity	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)		
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)		
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON		
HP Integrated Module with B	uetooth® 4.0/4.1/4.2/5.0 Wireless Technology		
Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant		
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.		
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW		
Bluetooth Software Supported	Microsoft Windows Bluetooth Software		
Link Topology			
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC60950-1/IEC62368-1 UL, CSA, and CE Mark		
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2		



Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)	
---	--

After-Market Options (availability may vary by region)

AFTER MARKET OPTIONS

Туре	Description	<u>Part #</u>
Memory	HP 4GB DDR4-3200 DIMM	13L78AA
	HP 8GB DDR4-3200 DIMM	13L76AA
	HP 16GB DDR4-3200 DIMM	13L74AA
	HP 32GB DDR4-3200 DIMM	13L72AA
Storage	HP PCIe Gen 4 NVME TLC M.2 512GB SSD	406L8AA
	HP PCIe Gen 4 NVME TLC M.2 1TB SSD	406L7AA
	HP 500GB 7200PRM SATA 6.0Gb/s 3.5" Hard Drive	QK554AA
	HP 1TB 7200rpm SATA 6Gb/s 3.5" Hard Drive	QK555AA
	HP PCIe Gen 4 NVME TLC M.2 1TB SSD	406L7AA
Graphics	NVIDIA T400 4GB GDDR6 3mDP	5Z7E0AA
	AMD Radeon RX 6300 2GB GDDR6 DP + HDMI	7Y6P7AA
Security	HP Business PC Security Lock V3 Kit	
	HP Keyed Cable Lock 10mm kit	T1A62AA
Adapters	HP PCIe x1 Parallel Port Card	N1M40AA
	HP HDMI Standard Cable Kit	T6F94AA
	HP USB to Serial Port Adapter	J7B60AA
	DisplayPort Cable Kit	VN567AA
Networking	Intel Ethernet I225-T1 GbE NIC Card	406L9AA
Input	HP Wired Desktop 320K Keyboard	9SR37AA
	HP 125 Wired Mouse	265A9AA
	HP 225 Wired Mouse and Keyboard Combo	286J4AA
	HP 225 Antimicrobial Wired Mouse and Keyboard Combo	286K3AA
	HP Wired Desktop 320K Keyboard	9SR37AA
	HP Wired Desktop 320M Mouse	9VA80AA
	HP 125 Wired Keyboard	266C9AA
	HP 125 Wired Mouse	265A9AA



Change Log

© Copyright 2024 HP Development Company, L.P.

The information contained herein is subject to change without notice. The only warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.

Microsoft and Windows are registered trademarks or trademarks of Microsoft Corporation in the U.S. and/or other countries. Intel, Celeron[®], Core, Pentium are registered trademarks or trademarks of Intel Corporation in the U.S. and/or other countries. Bluetooth is a trademark of its proprietor, used by HP Inc. under license. NVIDIA, GeForce, Kepler and NVS are trademarks and/or registered trademarks of NVIDIA Corporation in the U.S. and other countries. AMD and Radeon are trademarks of Advanced Micro Devices, Inc. DisplayPort[™] and the DisplayPort[™] logo are trademarks owned by the Video Electronics Standards Association (VESA[®]) in the United States and other countries.

Wi-Fi[®] is a registered trademark of Wi-Fi Alliance[®].

Date of change:	Version History:	Description of change:
	From v1 to v2	
	From v2 to v3	
	From v3 to v4	
	From v4 to v5	
	From v5 to v6	
	From v6 to v7	
	From v7 to v8	
	From v8 to v9	
	From v9 to v10	
	From v10 to v11	
	From v11 to v12	

